

4.0SMDJ24A



Uni-directional



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E230531

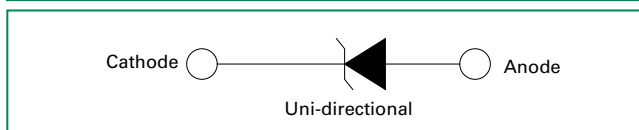
Maximum Ratings and Thermal Characteristics
(T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at T _A =25°C by 10/1000µs Waveform (Fig.2)(Note 1), (Note 2)	P _{PPM}	4000	W
Power Dissipation on Infinite Heat Sink at T _A =50°C	P _D	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I _{FSM}	300	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only	V _F	3.5	V
Operating Temperature Range	T _J	-65 to 150	°C
Storage Temperature Range	T _{STG}	-65 to 175	°C
Typical Thermal Resistance Junction to Lead	R _{θJL}	15	°C/W
Typical Thermal Resistance Junction to Ambient	R _{θJA}	75	°C/W

Notes:

1. Non-repetitive current pulse, per Fig. 4 and derated above T_J (initial) =25°C per Fig. 3.
2. Mounted on copper pad area of 0.31x0.31" (8.0 x 8.0mm) to each terminal.
3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.

Functional Diagram



Description

The 4.0SMDJ24A is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

Features

- 4000W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycles):0.01 %
- For surface mounted applications in order to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Built-in strain relief
- V_{BR} @ T_J = V_{BR} @ 25°C x (1 + αT x (T_J - 25)) (αT: Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- Fast response time: typically less than 1.0ps from 0V to BV min
- Excellent clamping capability
- Low incremental surge resistance
- High temperature to reflow soldering guaranteed: 260°C/40sec at terminals
- Meet MSL level1, per J-STD-020, LF maximum peak of 260°C
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

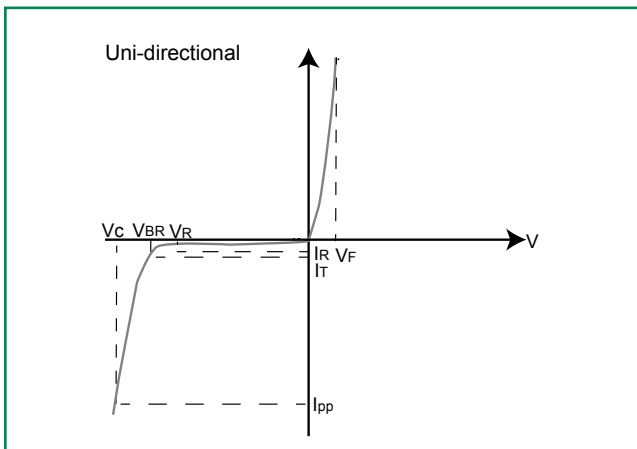
Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{CC} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Number	Marking	Reverse Stand off Voltage V _R (Volts)	Breakdown Voltage V _{BR} (Volts) @ I _T		Test Current I _T (mA)	Maximum Clamping Voltage V _c @ I _{pp} (10/1000µS) (V)	Maximum Clamping Voltage V _c @ I _{pp} (8/20µS) (V)	Maximum Peak Pulse Current I _{pp} (10/1000µS) (A)	Maximum Peak Pulse Current I _{pp} (8/20µS) (A)	Maximum Reverse Leakage I _R @ V _R (µA)
			MIN	MAX						
4.0SMDJ24A	4PEZ	24.0	26.70	29.50	1	38.9	51.0	103.0	650.0	2

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation – Max power dissipation

V_R Stand-off Voltage – Maximum voltage that can be applied to the TVS without operation

V_{BR} Breakdown Voltage – Maximum voltage that flows through the TVS at a specified test current (I_T)

V_C Clamping Voltage – Peak voltage measured across the TVS at a specified I_{ppm} (peak impulse current)

I_R Reverse Leakage Current – Current measured at V_R

V_F Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

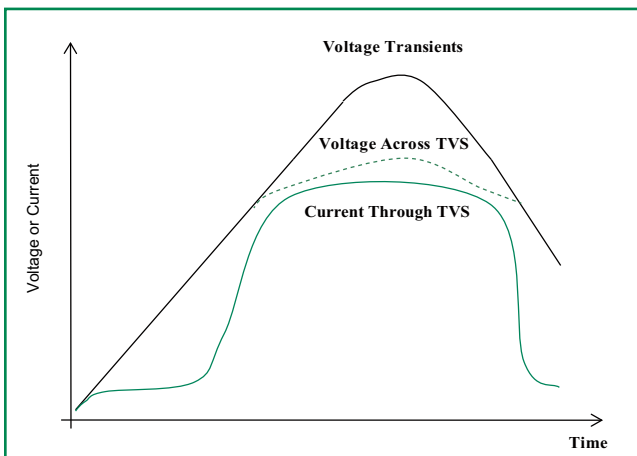
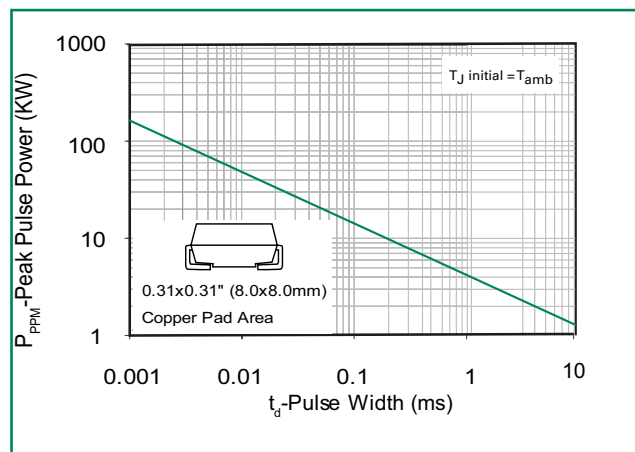


Figure 2 - Peak Pulse Power Rating



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Additional Information



Datasheet



Resources



Samples

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted) (Continued)

Figure 3 - Peak Pulse Power Derating Curve

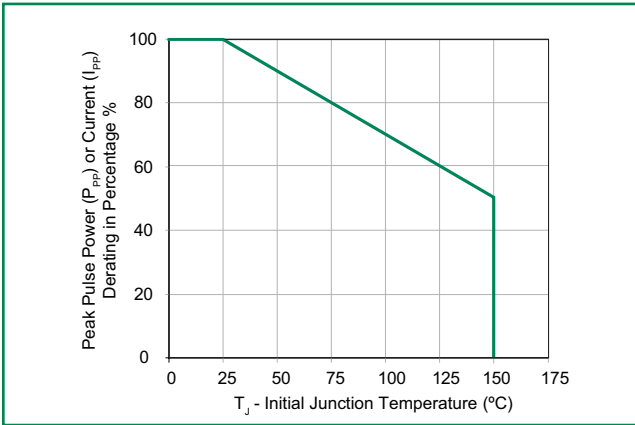


Figure 4 - Pulse Waveform

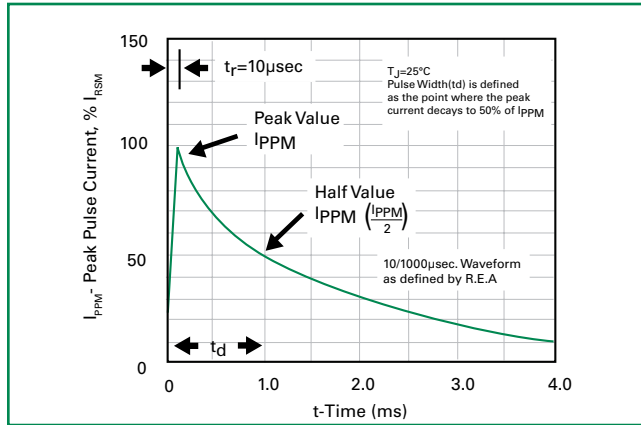


Figure 5 - Typical Transient Thermal Impedance

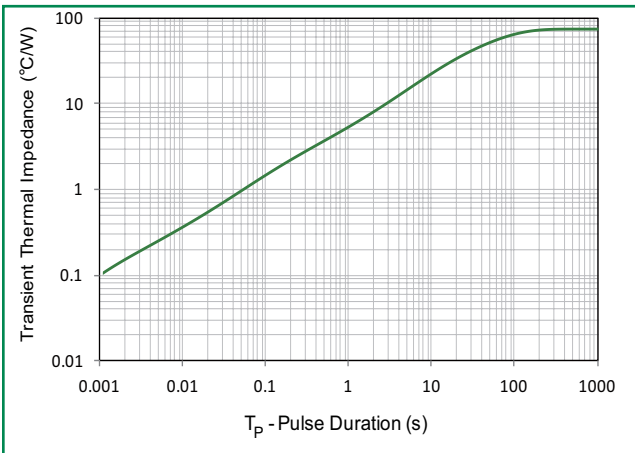


Figure 6 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only

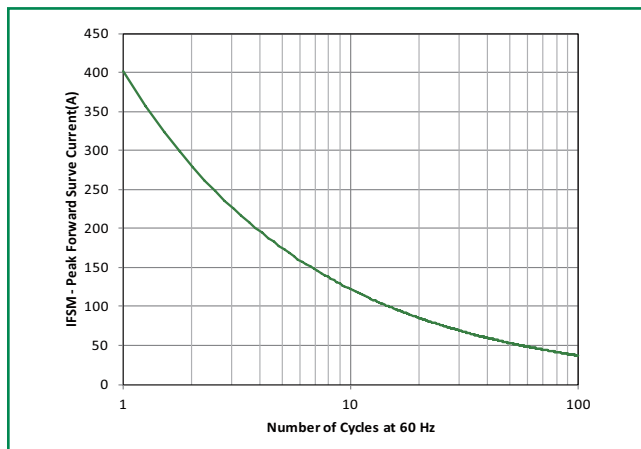
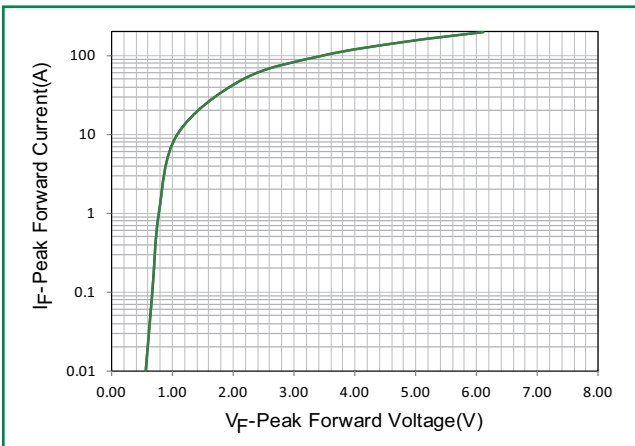
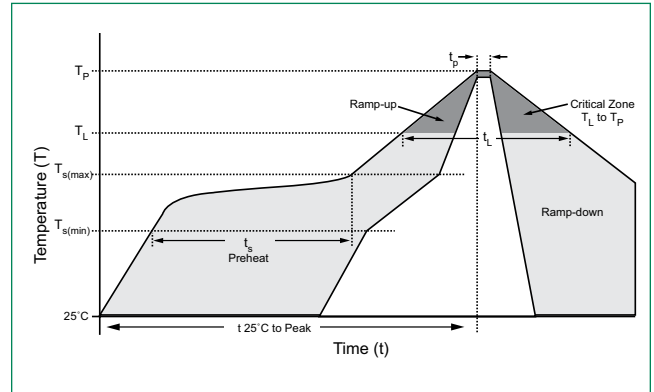


Figure 7 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)



Soldering Parameters

Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_A) to peak)		3°C/second max
$T_{s(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_A) (Liquidus)	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



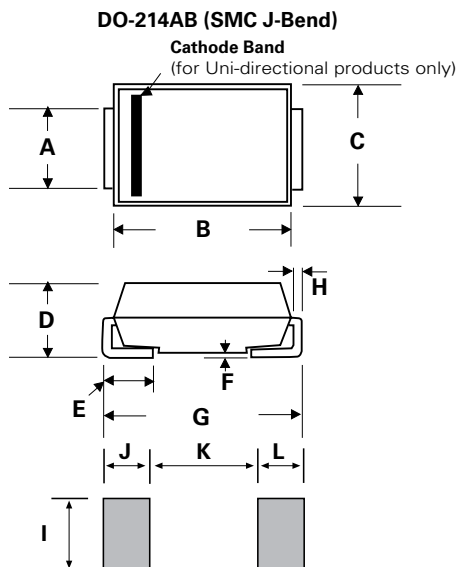
Physical Specifications

Weight	0.007 ounce, 0.21 grams
Case	JEDEC DO214AB. Molded plastic body over glass passivated junction
Polarity	Color band denotes positive end (cathode) except Bidirectional.
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

Environmental Specifications

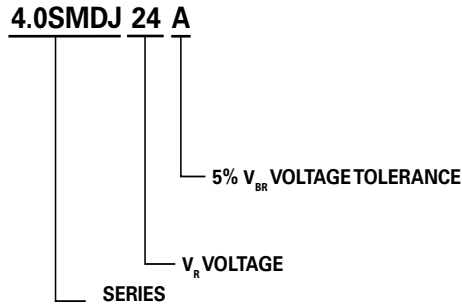
High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111

Dimensions

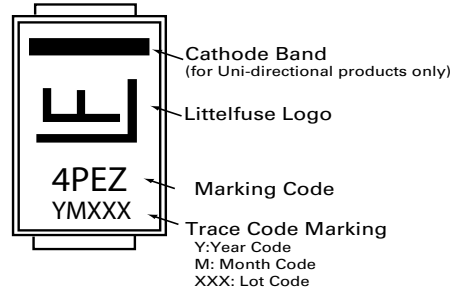


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.114	0.126	2.900	3.200
B	0.260	0.280	6.600	7.110
C	0.220	0.245	5.590	6.220
D	0.079	0.103	2.060	2.620
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.305	0.320	7.750	8.130
H	0.006	0.012	0.152	0.305
I	0.129	-	3.300	-
J	0.094	-	2.400	-
K	-	0.165	-	4.200
L	0.094	-	2.400	-

Part Numbering System



Part Marking System



Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
4.0SMDJ24A	DO-214AB	3000	Tape & Reel - 16mm tape/13" reel	EIA STD RS-481

Tape and Reel Specification

